

Description

Features

N-Channel: 30V 6A

 $R_{DS(ON)}$ =18.6m Ω (Typ.) @ V_{GS}=10V

 $R_{DS(ON)}$ =30m Ω (Typ.) @ V_{GS} =4.5V

P-Channel: -30V -6A

 $R_{DS(ON)}$ =27m Ω (Typ.) @ V_{GS}=-10V $R_{DS(ON)}$ =42m Ω (Typ.) @ V_{GS}=-4.5V

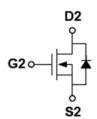
- Excellent Gate Charge x R_{DS(ON)} Product(FOM)
- Very Low On-resistance R_{DS(ON)}
- Fast Switching Speed

Application

- Battery Protection
- Load Switch
- Power Management







Schematic Diagram

Absolute Maximum Ratings (T_C=25 ℃ unless otherwise specified)

Symbol F	arameter Max. N-Channel Ma	x. P-Channel	Units		
V _{DSS}	Drain-Source Voltage		30	-30	V
Vgss	Gate-Source Voltage		±20	±20	V
I_	Continuous Drain Current	T _C = 25 °C	6	-6	Α
I _D		T _C = 100°C	5	-5	Α
I _{DM}	Pulsed Drain Current note1		30	-30	Α
PD	Power Dissipation	T _A = 25°C	2		W
RθJA	Thermal Resistance, Junction to Ambient		100		°C/W
T _J , T _{STG}	Operating and Storage Tempe	rature Range	-55 to	$^{\circ}$ C	



N-Channel Electrical Characteristics (Tc=25℃ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	teristic		1	•		
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V,I _D =250µA	30	-	_	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 30V, V_{GS} = 0V,$ $T_{J} = 25^{\circ}C$	-	-	1.0	μA
Igss	Gate to Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Charac	teristics			•	•	
V _{GS(th)}	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{D}=250\mu A$	1.0	1.55	3.0	V
	Static Drain-Source on-Resistance	V _{GS} =10V, I _D =6A	-	18.6	22	mΩ
R _{DS(on)}		V _{GS} =4.5V, I _D =5A	-	30	37	mΩ
g FS	Forward Transconductance	V _{DS} =5V, I _D =6A	-	15	-	S
Dynamic C	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 15V, V_{GS} = 0V,$ f = 1.0MHz	-	255	310	pF
Coss	Output Capacitance		-	45	60	pF
Crss	Reverse Transfer Capacitance		-	35	50	pF
Qg	Total Gate Charge	- V _{DS} =15V, I _D =6A,	-	5.2	-	nC
Qgs	Gate-Source Charge		-	2.5	-	nC
Q _{gd}	Gate-Drain("Miller") Charge	- V _{GS} =10V	-	1.0	-	nC
Switching	Characteristics					
t _{d(on)}	Turn-on Delay Time		-	4.5	-	ns
tr	Turn-on Rise Time	V _{GS} =10V, V _{DS} =15V,	-	2.5	-	ns
t _{d(off)}	Turn-off Delay Time	R_L =2.5Ω, R_{REN} =3Ω	-	14.5	-	ns
t f	Turn-off Fall Time		-	3.5	-	ns
Drain-Soul	rce Diode Characteristics and Maxim	um Ratings				
ls	Maximum Continuous Drain to Source Diode Forward Current		-	-	6	А
Ism	Maximum Pulsed Drain to Source Diode Forward Current		-	-	30	Α

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

^{2.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%



P-Channel Electrical Characteristics (T_C=25 °C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	cteristic			J		
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V,I _D = -250µA	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -30V, V_{GS} = 0V,$	-	-	-1	μΑ
I _{GSS}	Gate to Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Charac	cteristics		•	•	•	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-0.8	-1.32	-2.0	V
R _{DS(on)}	Static Drain-Source on-Resistance	V _{GS} =-10V, I _D =-6A	-	27	35	mΩ
		V _{GS} =-4.5V, I _D =-5A	-	42	50	
g FS	Forward Transconductance	V _{DS} =-5V, I _D = -6A	-	18	-	S
Dynamic C	Characteristics					
Ciss	Input Capacitance	- V _{DS} = -15V, V _{GS} = 0V, - f = 1.0MHz	-	760	-	pF
Coss	Output Capacitance		-	140	-	pF
Crss	Reverse Transfer Capacitance		-	95	-	pF
Qg	Total Gate Charge	V _{DS} = -15V, I _D = -6A, V _{GS} = -10V	-	13.6	-	nC
Qgs	Gate-Source Charge		-	2.5	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	3.2	-	nC
Switching	Characteristics					
t _{d(on)}	Turn-on Delay Time		-	11	-	ns
tr	Turn-on Rise Time	$V_{DS} = -15V, R_L = 2.3\Omega,$ $R_{GEN} = 3\Omega, V_{GS} = -10V,$	-	35	-	ns
t _{d(off)}	Turn-off Delay Time		-	30	-	ns
t _f	Turn-off Fall Time		-	10	-	ns
Drain-Sou	rce Diode Characteristics and Maxin	num Ratings				
ls	Maximum Continuous Drain to Source Diode Forward Current			-	-6	А
Ism	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-30	Α

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

^{2.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%